IEC QUALITY ASSESSMENT SYSTEM (IECQ)
covering Electronic Components,
Assemblies, Related Materials and Processes
For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Conformity

Approved Component – Capability

IECQ Certificate No.: IECQ-C BSI 15.0012

CB Certificate No.: 028/ICA

Schedule Number: IECQ-C BSI 15.0012-S **Rev No.:** 4 **Revision Date:** 2018/11/09 **Page** 1 **of** 2

Board Types:	Multilayer metal core boards with blind and/or buried vias (Type 6) Multilayer metal core boards without blind or buried vias (Type 5) Multilayer boards with blind and/or buried vias (Type 4) Multilayer boards without blind or buried vias (Type 3) Double-Sided boards (Type 2) Single-Sided Boards (Type 1)	IPC 6012 Class 3*
	Multilayer rigid and flexible material combinations containing three or more conductive layers with plated through holes (Type 4) Multilayer flexible printed wiring containing three or more conductive layers with plated through holes, with or without stiffeners (Type 3) Double-sided flexible printed wiring containing two conductive layers with plated through holes, with or without stiffeners (Type 2) Single-sided flexible printed wiring containing one conductive layer, with or without stiffeners (Type 1)	IPC 6013 Class 3*

*With reduced sampling for structural integrity (micro-section) in accordance with IECQ OD 301

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Base Materials:	Epoxide Woven Glass (IPC-4101) Polyimide Film (IPC-4204)
Board Size:	609 mm x 457 mm Maximum
Conductors:	Minimum Width: 0.075mm Minimum Spacing: 0.09mm
Number of Layers:	30 Maximum
Plated-through hole diameter:	0.25 mm Minimum drilled
Aspect ratio:	8 : 1 Maximum
Finishes:	Hot Air Solder Levelled SnPb Electroplated SnPb Fused SnPb Electroless Nickel / Immersion Gold Immersion Tin Photoimagable liquid polymer solder resist Marking ink
Additional:	Bonded Heatsinks: Anodized Aluminium 2.5µm gold on 5µm nickel on copper 2.5µm gold on Copper Blind and Buried Via Holes